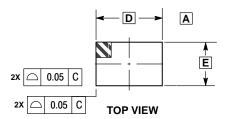


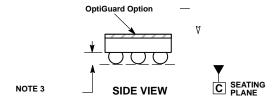
MECHANICAL

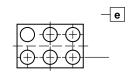


WLCSP6, 1.46x0.96 CASE 567BB **ISSUE O**

DATE 26 JUL 2010





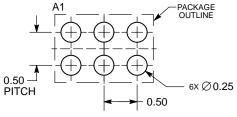


BOTTOM VIEW

- NOTES: 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.56	0.72	
A1	0.21	0.27	
A2	0.42 REF		
b	0.29	0.35	
D	1.46 BSC		
E	0.96 BSC		
٥	0.50 BSC		

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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